

**S/N unassigned**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Qing Ma

Examiner: Unassigned

Serial No.: Unassigned

Group Art Unit: Unassigned

Filed: Herewith

Docket No.: 884.803US2

Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE  
PACKAGE HAVING A MOISTURE BARRIER STRUCTURE

Assignee: Intel Corporation

Customer No.: 21186

---

**PRELIMINARY AMENDMENT UNDER 37 CFR § 1.115**

MS Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Prior to examining the above-captioned divisional application, please amend the application as follows.